

RoHS

COMPLIANT

HALOGEN

FREE

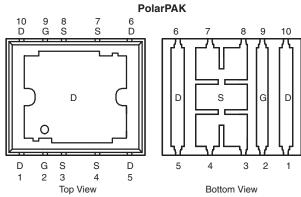
Available

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET with Schottky Diode

PRODUCT SUMMARY								
		I _D (A) ^a						
V _{DS} (V)	R _{DS(on)} (Ω) ^e	Silicon Limit	Package Limit	Q _g (Тур.)				
30	0.0024 at V _{GS} = 10 V	175	60	50 nC				
30	0.0033 at $V_{GS}\!=\!4.5V$	149	60	50 110				

Package Drawing www.vishay.com/doc?72945

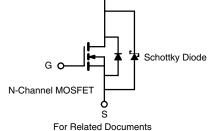


FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- SkyFET™ Monolithic TrenchFET® Power MOSFET and Schottky Diode
- Ultra Low Thermal Resistance Using Top-Exposed PolarPAK[®] Package for Double-Sided Cooling
- Leadframe-Based New Encapsulated Package - Die Not Exposed
 - Same Layout Regardless of Die Size
- Low Q_{ad}/Q_{as} Ratio Helps Prevent Shoot-Through
- 100 % R_a and UIS Tested
- Compliant to RoHS directive 2002/95/EC

APPLICATIONS

- Synchronous Rectification
- DC/DC
- Low-Side Switch



D

www.vishay.com/ppg?68626

Top surface is connected to pins 1, 5, 6, and 10 Ordering Information: SiE726DF-T1-E3 (Lead (Pb)-free) SiE726DF-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted Parameter Symbol Limit Unit Drain-Source Voltage 30 V_{DS} v \overline{V}_{GS} Gate-Source Voltage ± 20 175 (Silicon Limit) T_C = 25 °C 60^a (Package Limit) T_C = 70 °C Continuous Drain Current (T_J = 150 °C) I_D 60^a <u>3</u>5^{b, c} T_A = 25 °C 28^{b, c} T_A = 70 °C А Pulsed Drain Current 80 I_{DM} T_C = 25 °C 60^a Continuous Source-Drain Diode Current I_{S} 4.3^{b, c} T_A = 25 °C Single Pulse Avalanche Current I_{AS} 50 L = 0.1 mHAvalanche Energy 125 E_{AS} mJ T_C = 25 °C 125 T_C = 70 °C 80 Maximum Power Dissipation P_D W T_A = 25 °C 5.2^{b, c} T_A = 70 °C 3.3^{b, c} T_J, T_{stg} - 55 to 150 Operating Junction and Storage Temperature Range °C 260 Soldering Recommendations (Peak Temperature)^{d, e} Notes:

a. Package limited. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

e. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

d. See Solder Profile (www.vishay.com/ppg?73257). The PolarPAK is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

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THERMAL RESISTANCE RATINGS									
Parameter		Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient ^{a, b}	$t \le 10 s$	R _{thJA}	20	24					
Maximum Junction-to-Case (Drain Top)	Steady State	R _{thJC} (Drain)	0.8	1	°C/W				
Maximum Junction-to-Case (Source) ^{a, c}	kimum Junction-to-Case (Source) ^{a, c}		2.2	2.7					

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. Maximum under Steady State conditions is 68 °C/W.
c. Measured at source pin (on the side of the package).

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			•			
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 1 mA$	30			V
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1		3	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V		0.120	0.5	mA
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$		1.0	10	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	25			Α
	R _{DS(on)}	V _{GS} = 10 V, I _D = 25 A		0.0020	0.0024	Ω
Drain-Source On-State Resistance ^a		V _{GS} = 4.5 V, I _D = 25 A		0.0026	0.0033	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 25 A		90		S
Dynamic ^b			•	•		
Input Capacitance	C _{iss}			7400		pF
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		1100		
Reverse Transfer Capacitance	C _{rss}			400		
Tatal Oata Oharma	Qg	$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		105	160	
Total Gate Charge				50	75	
Gate-Source Charge	Q _{gs}	V_{DS} = 15 V, V_{GS} = 4.5 V, I_{D} = 20 A		22		nC
Gate-Drain Charge	Q _{gd}			12		
Gate Resistance	Rg	f = 1 MHz		1	2	Ω
Turn-On Delay Time	t _{d(on)}			60	90	
Rise Time	t _r	$\label{eq:V_DD} \begin{array}{l} V_{DD} = 15 \; V, R_{L} = 1.5 \; \Omega \\ I_{D} \cong 10 \; A, V_{GEN} = 4.5 \; V, R_{g} = 1 \; \Omega \end{array}$		35	55	
Turn-Off Delay Time	t _{d(off)}			55	85	
Fall Time	t _f			30	45	
Turn-On Delay Time	t _{d(on)}			20	30	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	15	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 10 A, V_GEN = 10 V, R_g = 1 Ω		55	85	
Fall Time	t _f			10	15	
Drain-Source Body Diode and Schottky	Characteristi	ics	•			
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			60	٨
Pulse Diode Forward Current ^a	I _{SM}				80	A
Body Diode Voltage	V _{SD}	I _S = 2 A		0.37	0.45	V
Body Diode Reverse Recovery Time	t _{rr}			40	60	ns
Body Diode Reverse Recovery Charge Q _{rr}				30	45	nC
Reverse Recovery Fall Time	t _a	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C		19		ns
Reverse Recovery Rise Time	t _b			21		

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %

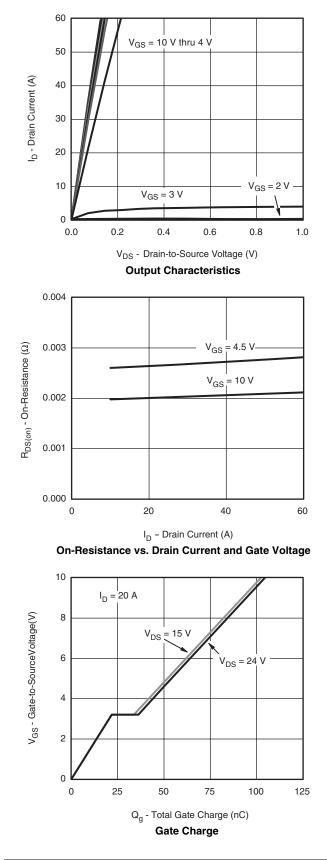
b. Guaranteed by design, not subject to production testing.

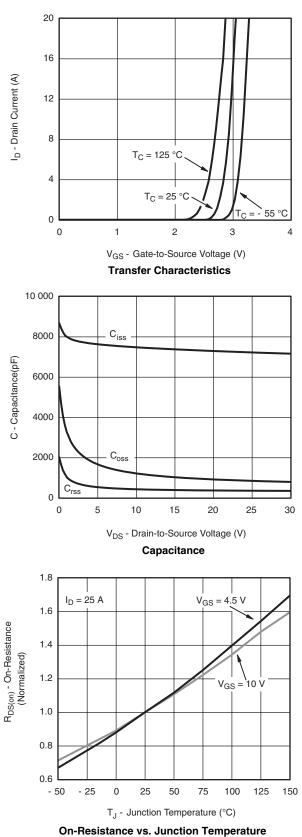
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



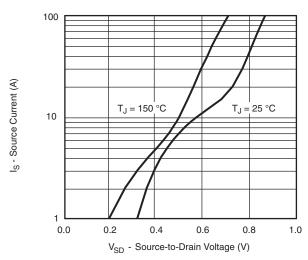


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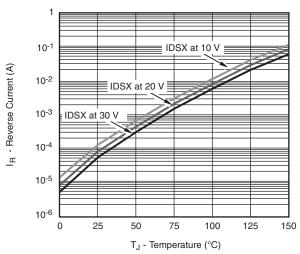
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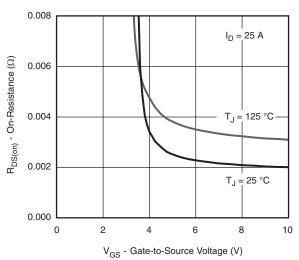
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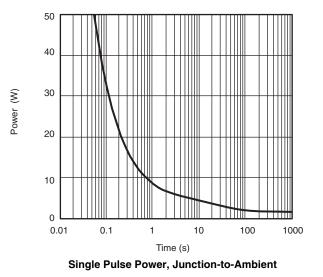
Source-Drain Diode Forward Voltage

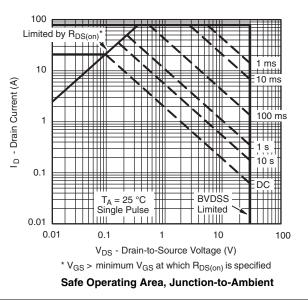


Reverse Current vs. Junction Temperature



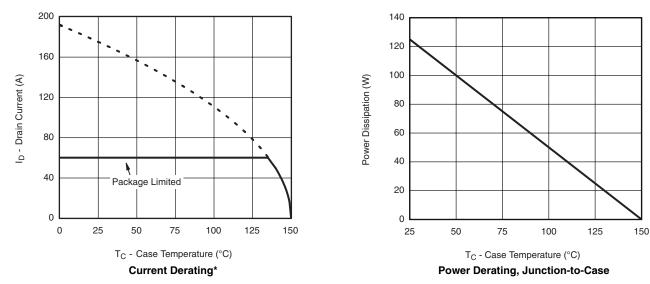
On-Resistance vs. Gate-to-Source Voltage







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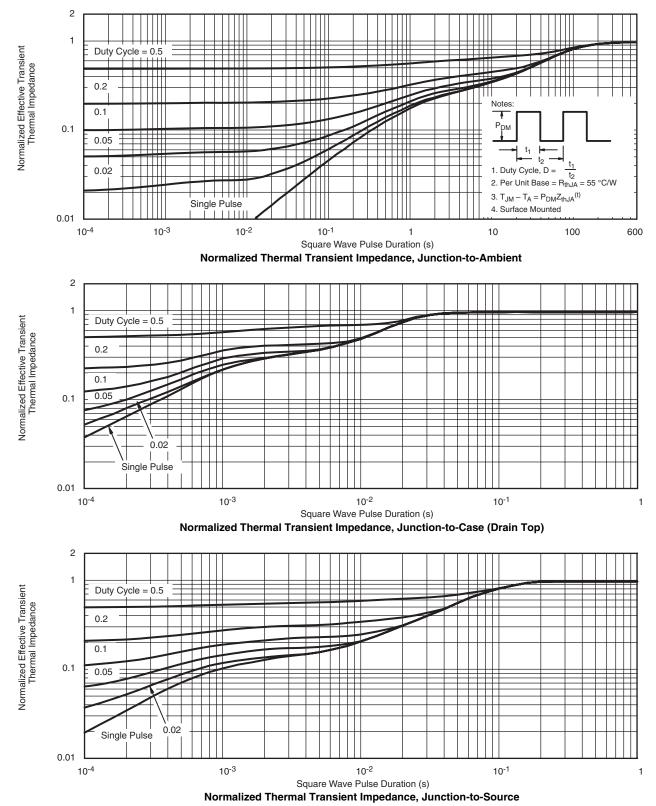
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



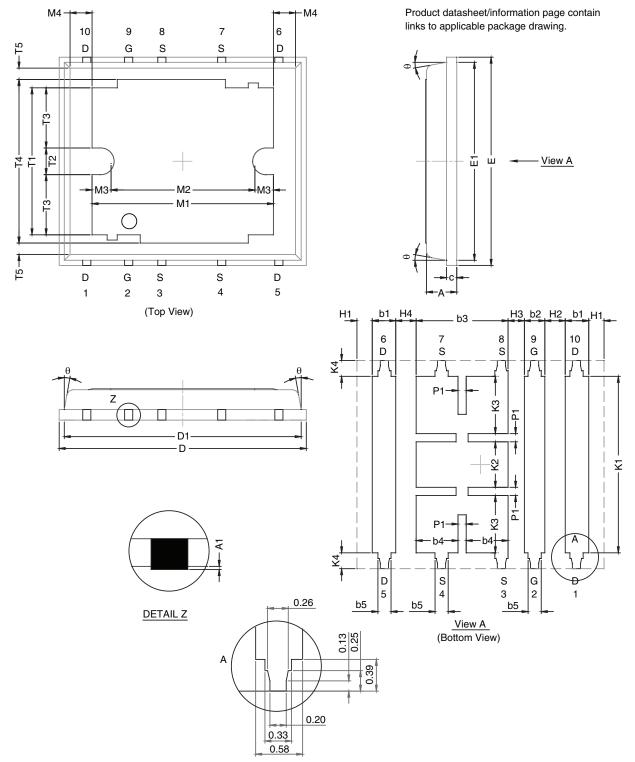
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg268626.



Package Information

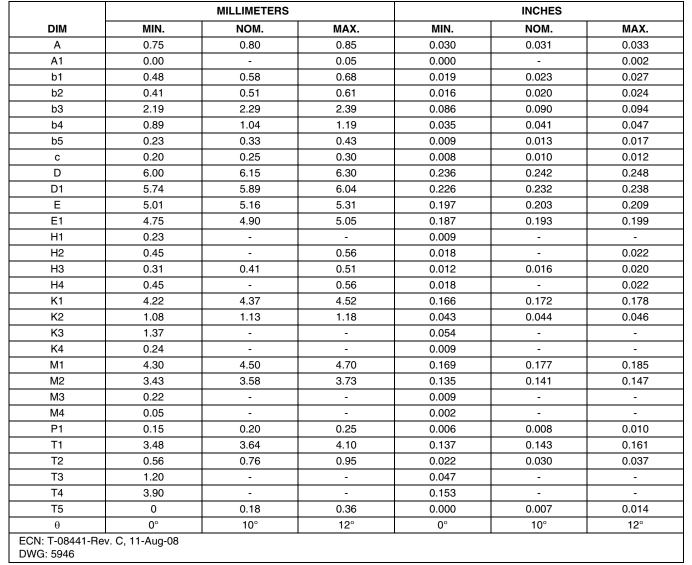
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POLARPAK™ OPTION L



Package Information

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Notes

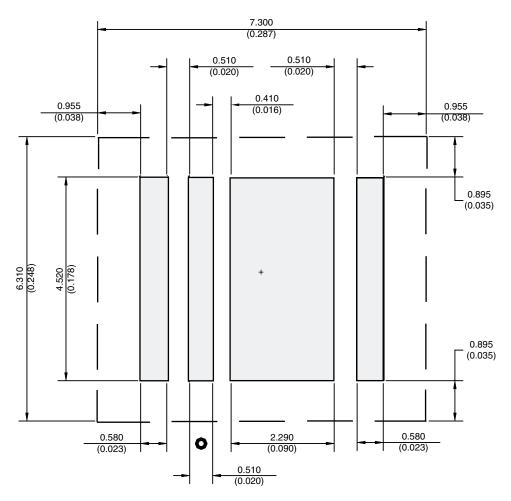
Millimeters govern over inches.



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RECOMMENDED MINIMUM PADS FOR PolarPAK® Option L and S



Recommended Minimum for PolarPAK Option L and S Dimensions in mm/(Inches) No External Traces within Broken Lines Dot indicates Gate Pin (Part Marking)

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